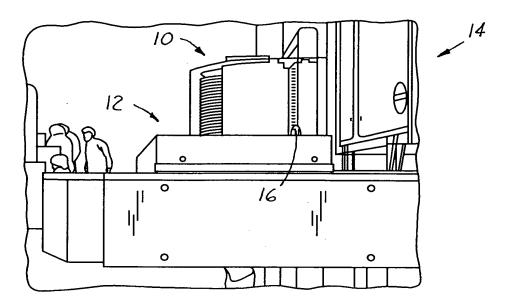
Inventor(s): Tseng, et al Serial No.: To Be Assigned

Filed: Herewith

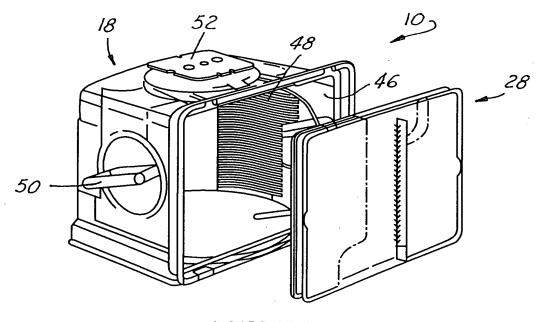
For: Wafer Transport Pod With Linear Door Opening Mechanism Attorney Docket No.: 67,200-674



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(PRIOR ART) FIG₁



(PRIOR ART)
FIG 2



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Attorney Docket No.: 67,200-674

